

REMARKS

This is in response to the Office Action dated May 4, 2005. New claims 15-16 have been added. Thus, claims 1-16 are now pending.

Claim 1 stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by Papathomas. This Section 102(b) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires that “said solder resist is provided over part of the interconnection pattern but leaves the interconnection pattern exposed in an area that is to be connected to the semiconductor element via the projecting electrode, and wherein the insulating resin containing the anti-repellant covers at least edge portions of the solder resist.” For example and without limitation, Fig. 1(e) of the instant application illustrates that solder resist 5 is provided over part of the interconnection pattern 2 but leaves the interconnection pattern 2 exposed in an area that is to be connected to the semiconductor element 3 via the projecting electrode 6, and wherein the insulating resin 7 containing the anti-repellant covers at least edge portions of the solder resist 5. See also Fig. 2 for example and without limitation.

Papathomas fails to disclose or suggest the aforesaid quoted and underlined features of amended claim 1. Papathomas fails to disclose or suggest a solder resist that is provided over part of the interconnection pattern but leaves the interconnection pattern exposed in an area that is to be connected to the semiconductor element via a projecting electrode. Papathomas also fails to disclose or suggest an insulating resin containing an anti-repellant covering at least edge portions of the solder resist as required by claim 1. Papathomas is entirely unrelated to the invention of amended claim 1 in these respects.

Claim 7 as amended requires that "said solder resist is provided over part of the interconnection pattern but leaves the interconnection pattern exposed in an area that is to be connected to the semiconductor element via the projecting electrode, and wherein the insulating resin containing the anti-repellant covers at least edge portions of the solder resist." Papathomas fails to disclose or suggest these features of amended claim 7.

Claim 15 requires "said solder resist coating the interconnection pattern except for an area that is connected to the semiconductor element via the projecting electrode, said resin fillet covering edge portions of the solder resist so that the interconnection pattern is not made exposed in an area that is not covered with the solder resist." Again, Papathomas fails to disclose or suggest these features of claim 15.

Claim 16 requires "said solder resist coating the interconnection pattern except for an area that is connected to the semiconductor element via the projecting electrode, the insulating resin containing the resin anti-repellant covering edge portions of the solder resist so that the interconnection pattern is not made exposed in an area that is not covered with the solder resist." Again, Papathomas fails to disclose or suggest these features of claim 16.

It is respectfully requested that all rejections be withdrawn. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

SEKO

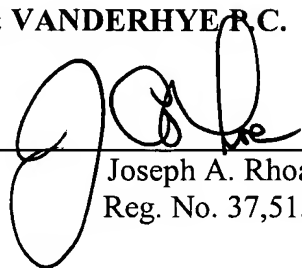
Appl. No. 10/668,234

August 4, 2005

Respectfully submitted,

NIXON & VANDERHYE P.C.

By: _____

A handwritten signature in black ink, appearing to read 'JAR', is written over a horizontal line.

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